

TLP184(SE

1. Applications

- Programmable Logic Controllers (PLCs)
- Private Branch Exchanges (PBXs)

2. General

The TLP184(SE is a AC input type photocoupler that consist of a photo transistor optically coupled to two gallium arsenide infrared emitting diodes.

The TLP184(SE is housed in the very small and thin SO6 package, it has a high noise immunity and a high isolation voltage.

Since the TLP184(SE is smaller than DIP package, it's suitable for high-density surface mounting application such as Hybrid ICs.

3. Features

- (1) Collector-emitter voltage: 80 V (min)
- (2) Current transfer ratio: 50% (min)
Rank GB: 100% (min)
- (3) Isolation voltage: 3750 Vrms (min)
- (4) Operating temperature: -55 to 110 °C
- (5) Safety standards

UL-approved: UL1577, File No.E67349

cUL-approved: CSA Component Acceptance Service No.5A File No.E67349

VDE-approved: EN60747-5-5 (**Note 1**)

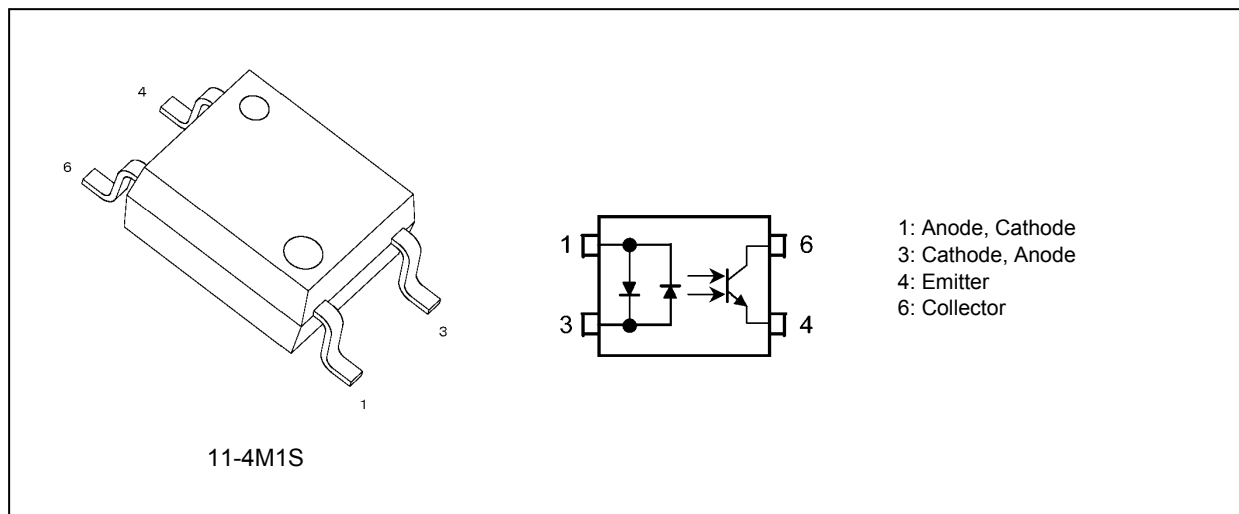
CQC-approved: GB4943.1, GB8898 Thailand Factory



仅适用于海拔 2000m 以下地区安全使用

Note 1: When an EN60747-5-5 approved type is needed, please designate the **Option (V4)**.

4. Packaging and Pin Assignment



Start of commercial production

2013-01

5. Principle of Operation

5.1. Mechanical Parameters

Characteristics	Min	Unit
Creepage distances	5.0	mm
Clearance	5.0	
Internal isolation thickness	0.4	

6. Absolute Maximum Ratings (Note) (Unless otherwise specified, T_a = 25 °C)

	Characteristics	Symbol	Note	Rating	Unit
LED	R.M.S. forward current	I _{F(RMS)}		±50	mA
	Input forward current derating (T _a ≥ 90 °C)	ΔI _F /ΔT _a		-1.5	mA/°C
	Input forward current (pulsed)	I _{FP}	(Note 1)	±1	A
	Input power dissipation	P _D		100	mW
	Junction temperature	T _J		125	°C
Detector	Collector-emitter voltage	V _{CEO}		80	V
	Emitter-collector voltage	V _{ECO}		7	V
	Collector current	I _C		50	mA
	Collector power dissipation	P _C		150	mW
	Collector power dissipation derating (T _a ≥ 25 °C)	ΔP _C /ΔT _a		-1.5	mW/°C
	Junction temperature	T _J		125	°C
Common	Operating temperature	T _{opr}		-55 to 110	°C
	Storage temperature	T _{stg}		-55 to 125	°C
	Lead soldering temperature (10 s)	T _{sol}		260	°C
	Total power dissipation	P _T		200	mW
	Input power dissipation derating (T _a ≥ 25 °C)	ΔP _D /ΔT _a		-2.0	mW/°C
	Isolation voltage AC, 60 s, R.H. ≤ 60%	BV _S	(Note 2)	3750	V _{rms}

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Pulse width (PW) ≤ 100 μs, f = 100 Hz

Note 2: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.

7. Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

	Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
LED	Input forward voltage	V _F		I _F = ±10 mA	1.1	1.25	1.4	V
	Input capacitance	C _t		V = 0 V, f = 1 MHz	—	60	—	pF
Detector	Collector-emitter breakdown voltage	V _{(BR)CEO}		I _C = 0.5 mA	80	—	—	V
	Emitter-collector breakdown voltage	V _{(BR)ECO}		I _E = 0.1 mA	7	—	—	V
	Dark Current	I _{DARK}		V _{CE} = 48 V	—	0.01	0.08	μA
				V _{CE} = 48 V, T _a = 85 °C	—	2	50	μA
	Collector-emitter capacitance	C _{CE}		V = 0 V, f = 1 MHz	—	10	—	pF

8. Coupled Electrical Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Current transfer ratio	I _C /I _F	(Note 1)	I _F = ±5 mA, V _{CE} = 5 V	50	—	600	%
			I _F = ±5 mA, V _{CE} = 5 V, Rank GB	100	—	600	
Saturated current transfer ratio	I _C /I _{F(sat)}		I _F = ±1 mA, V _{CE} = 0.4 V	—	60	—	
			I _F = ±1 mA, V _{CE} = 0.4 V, Rank GB	30	—	—	
Collector-emitter saturation voltage	V _{CE(sat)}		I _C = 2.4 mA, I _F = ±8 mA	—	—	0.3	V
			I _C = 0.2 mA, I _F = ±1 mA	—	0.2	—	
			I _C = 0.2 mA, I _F = ±1 mA, Rank GB	—	—	0.3	
OFF-state collector current	I _{C(off)}		V _F = ±0.7 V, V _{CE} = 48 V	—	1	10	μA
Collector current ratio	I _{C(ratio)}		See Fig. 8.1 I _C (I _F = -5 mA) / I _C (I _F = 5 mA)	0.33	1	3	—

Note 1: See Table 8.1 for current transfer ratio.

Table 8.1 Current Transfer Ratio (CTR) Rank (Note) (Unless otherwise specified, T_a = 25 °C)

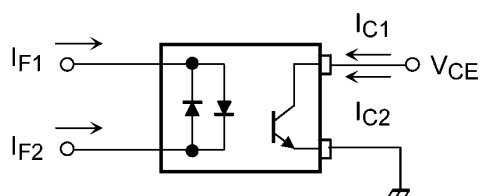
Rank	Test Condition	Current transfer ratio I _C /I _F Min	Current transfer ratio I _C /I _F Max	Marking of Classification	Unit
Blank	I _F = ±5 mA, V _{CE} = 5 V	50	600	Blank, YE, GR, GB, BL	%
Y		50	150	YE	
GR		100	300	GR	
GB		100	600	GB	
BL		200	600	BL	

Note: Specify both the part number and a rank in this format when ordering.

Example: TLP184(GB,SE)

For safety standard certification, however, specify the part number alone.

Example: TLP184(GB,SE: TLP184)



$$I_C(\text{ratio}) = \frac{I_{C2}(I_F = I_{F2}, V_{CE} = 5 \text{ V})}{I_{C1}(I_F = I_{F1}, V_{CE} = 5 \text{ V})}$$

Fig. 8.1 Collector Current Ratio Test Circuit

9. Isolation Characteristics (Unless otherwise specified, T_a = 25 °C)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Total capacitance (input to output)	C _S	(Note 1)	V _S = 0 V, f = 1 MHz	—	0.8	—	pF
Isolation resistance	R _S	(Note 1)	V _S = 500 V, R.H. ≤ 60 %	1 × 10 ¹²	10 ¹⁴	—	Ω
Isolation voltage	BV _S	(Note 1)	AC, 60 s	3750	—	—	Vrms
			AC, 1 s in oil	—	10000	—	
			DC, 60 s in oil	—	10000	—	Vdc

Note 1: This device is considered as a two-terminal device: Pins 1 and 3 are shorted together, and pins 4 and 6 are shorted together.

10. Switching Characteristics (Unless otherwise specified, $T_a = 25\text{ }^\circ\text{C}$)

Characteristics	Symbol	Note	Test Condition	Min	Typ.	Max	Unit
Rise time	t_r		$V_{CC} = 10\text{ V}$, $I_C = 2\text{ mA}$, $R_L = 100\ \Omega$	—	2	—	μs
Fall time	t_f			—	3	—	
Turn-on time	t_{on}			—	3	—	
Turn-off time	t_{off}			—	3	—	
Turn-on time	t_{on}	See Fig. 10.1	$V_{CC} = 5\text{ V}$, $I_F = 16\text{ mA}$, $R_L = 1.9\text{ k}\Omega$	—	0.5	—	
Storage time	t_s			—	30	—	
Turn-off time	t_{off}			—	50	—	

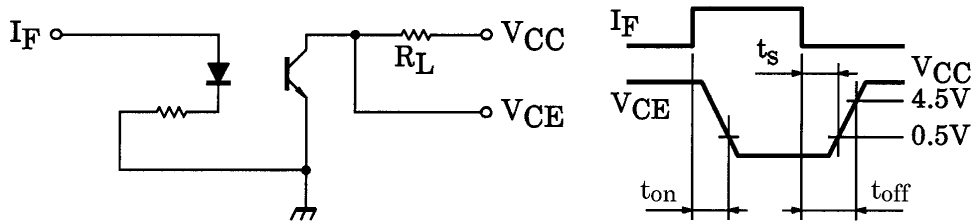


Fig. 10.1 Switching Time Test Circuit and Waveform

11. Characteristics Curves (Note)

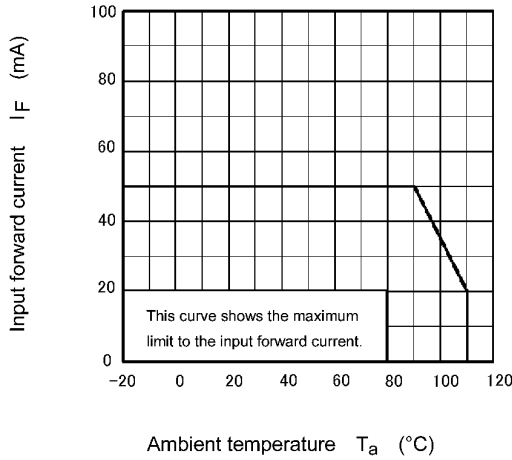


Fig. 11.1 $I_F - T_a$

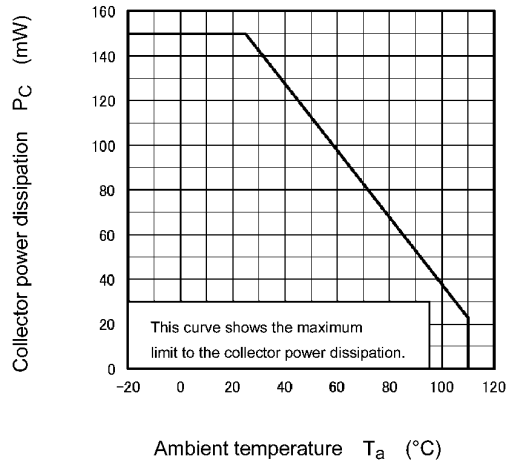


Fig. 11.2 $P_C - T_a$

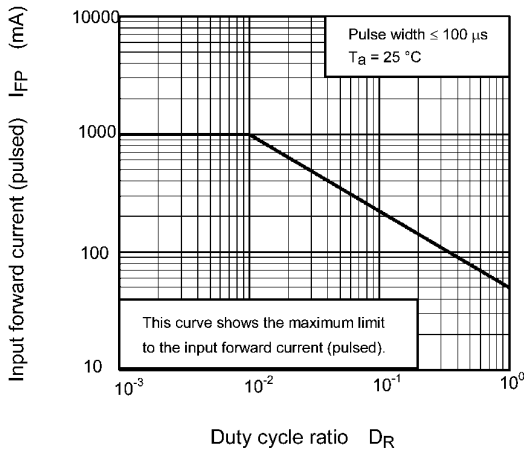


Fig. 11.3 $I_{FP} - D_R$

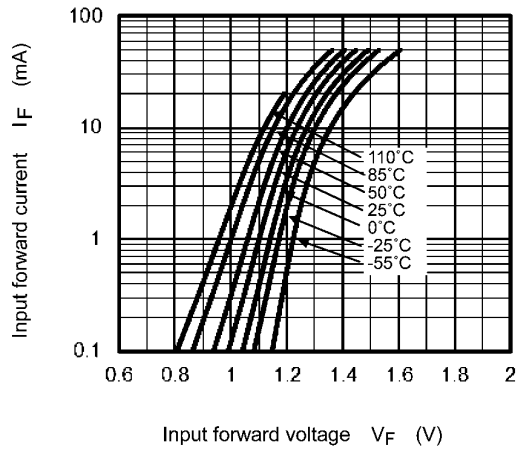


Fig. 11.4 $I_F - V_F$

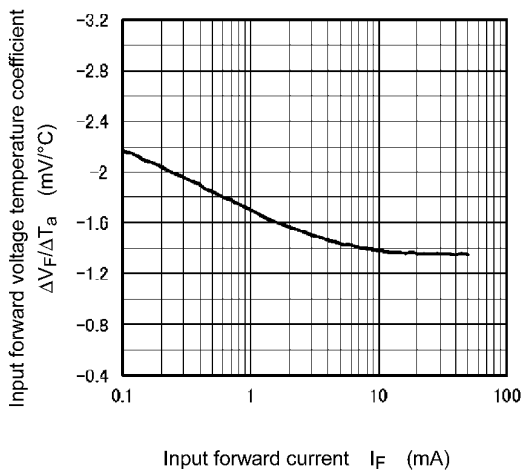


Fig. 11.5 $\Delta V_F / \Delta T_a - I_F$

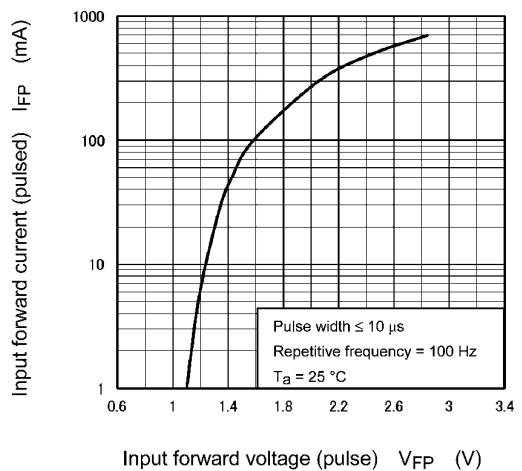


Fig. 11.6 $I_{FP} - V_{FP}$

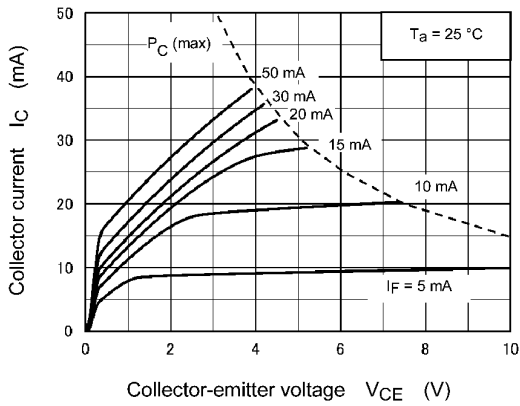


Fig. 11.7 $I_C - V_{CE}$

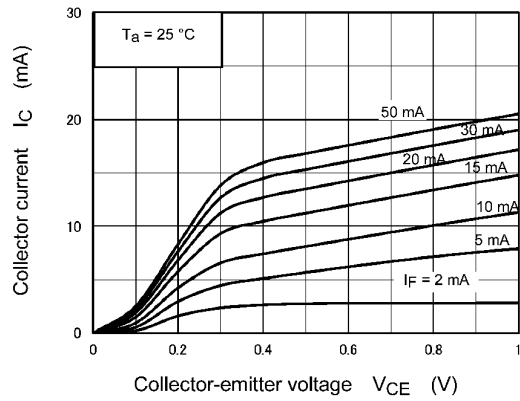


Fig. 11.8 $I_C - V_{CE}$

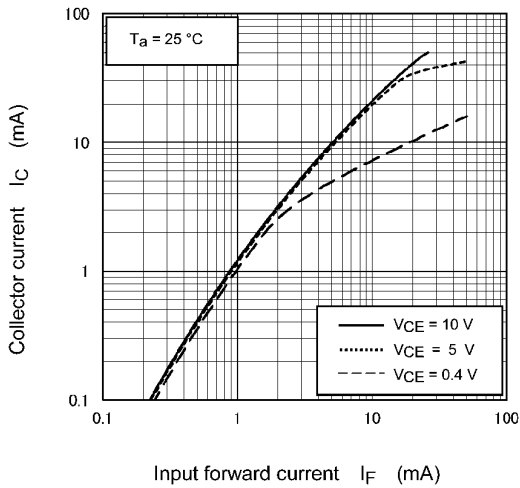


Fig. 11.9 $I_C - I_F$

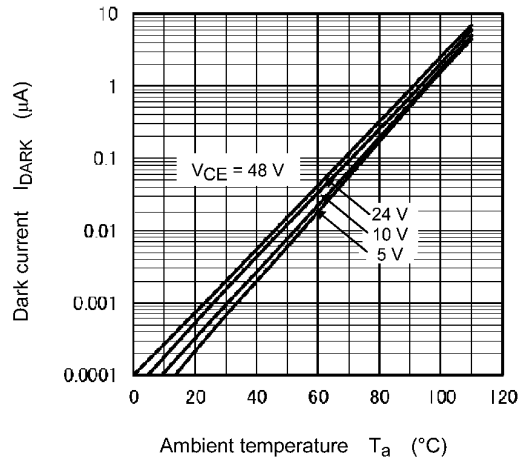


Fig. 11.10 $I_{DARK} - T_a$

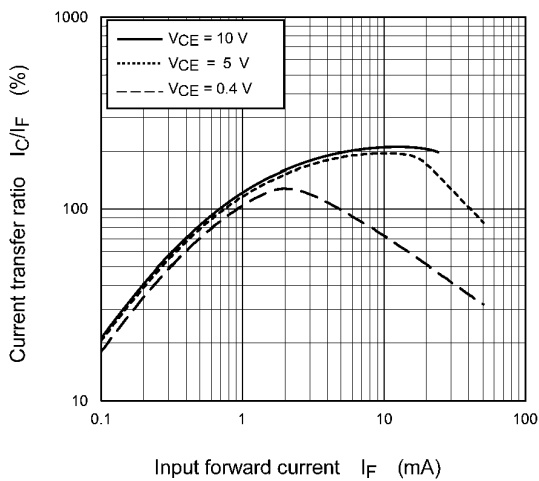


Fig. 11.11 $I_C/I_F - I_F$

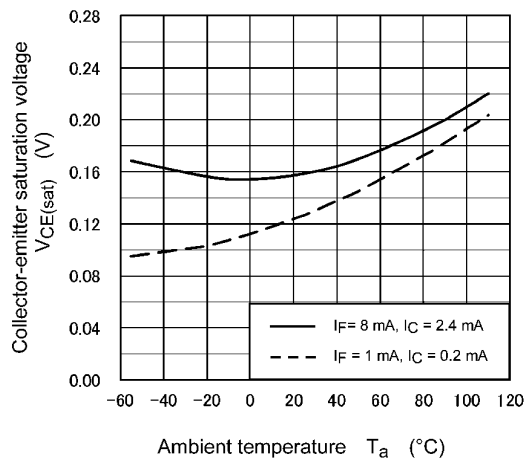


Fig. 11.12 $V_{CE(sat)} - T_a$

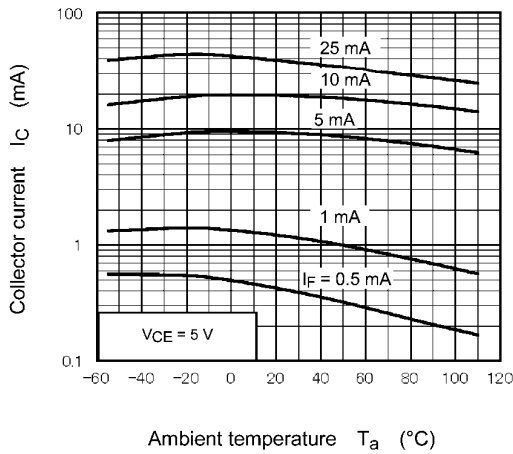


Fig. 11.13 $I_C - T_a$

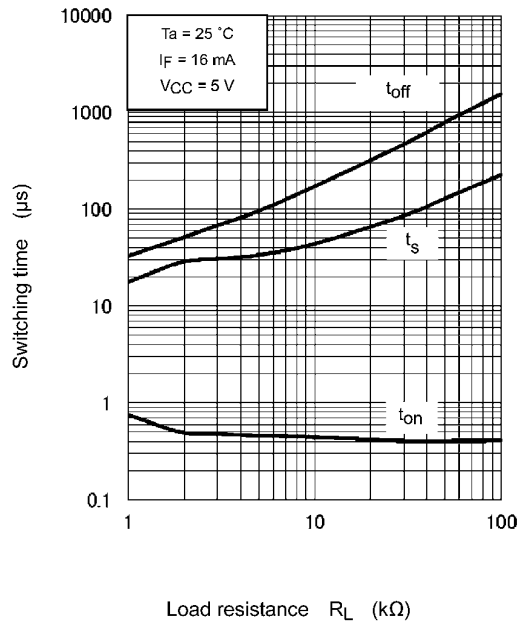


Fig. 11.14 Switching Time - R_L

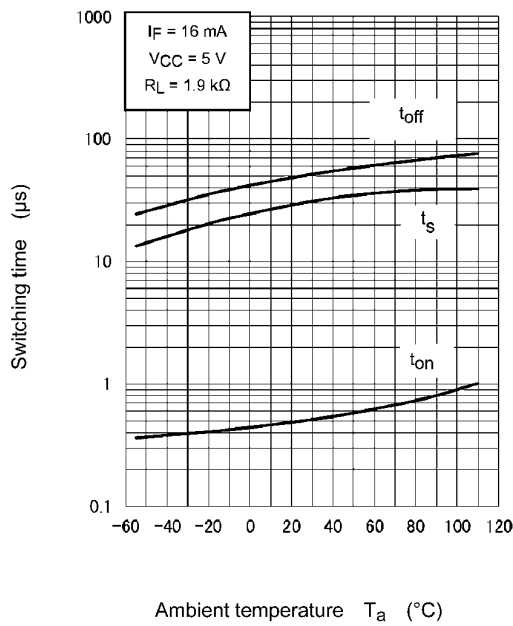


Fig. 11.15 Switching Time - T_a

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

12. Soldering and Storage

12.1. Precautions for Soldering

The soldering temperature should be controlled as closely as possible to the conditions shown below, irrespective of whether a soldering iron or a reflow soldering method is used.

- When using soldering reflow.

The soldering temperature profile is based on the package surface temperature.

(See the figure shown below, which is based on the package surface temperature.)

Reflow soldering must be performed once or twice.

The mounting should be completed with the interval from the first to the last mountings being 2 weeks.

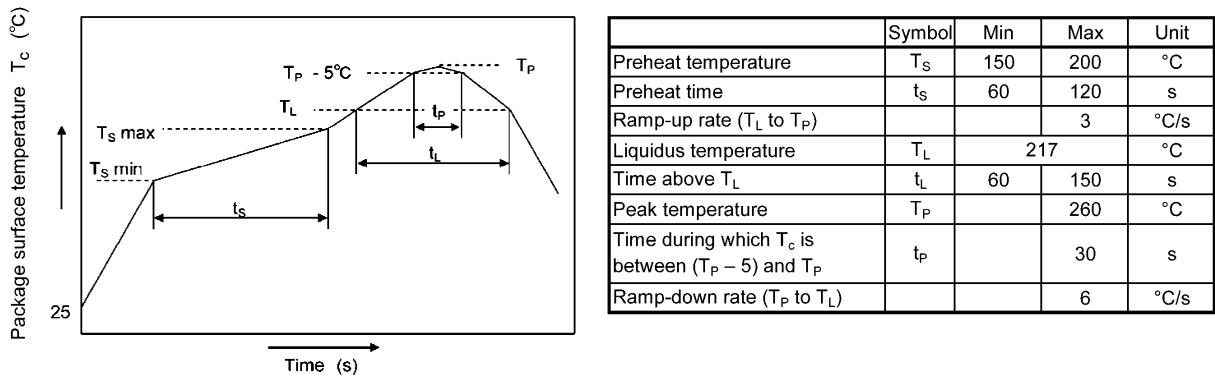


Fig. 12.1.1 An Example of a Temperature Profile When Lead(Pb)-Free Solder Is Used

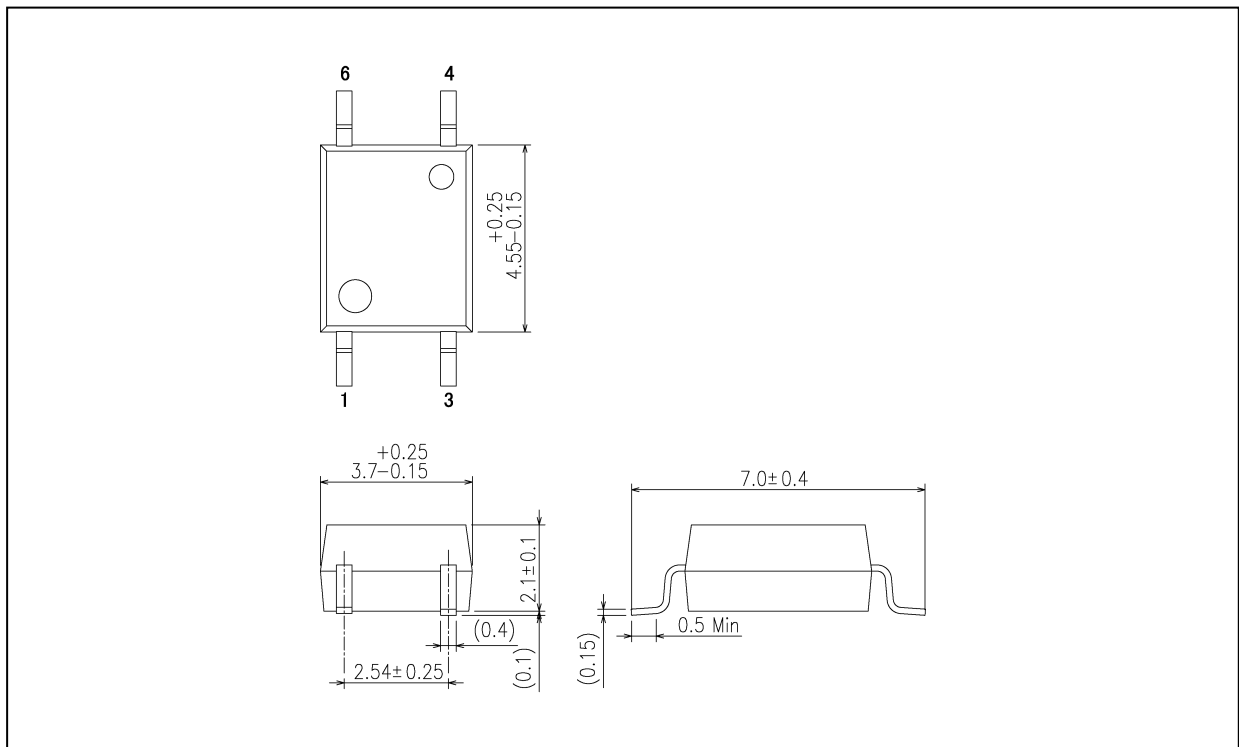
- When using soldering flow
Preheat the device at a temperature of 150 °C (package surface temperature) for 60 to 120 seconds.
Mounting condition of 260 °C within 10 seconds is recommended.
Flow soldering must be performed once.
- When using soldering Iron
Complete soldering within 10 seconds for lead temperature not exceeding 260 °C or within 3 seconds not exceeding 350 °C
Heating by soldering iron must be done only once per lead.

12.2. Precautions for General Storage

- Avoid storage locations where devices may be exposed to moisture or direct sunlight.
- Follow the precautions printed on the packing label of the device for transportation and storage.
- Keep the storage location temperature and humidity within a range of 5 °C to 35 °C and 45 % to 75 %, respectively.
- Do not store the products in locations with poisonous gases (especially corrosive gases) or in dusty conditions.
- Store the products in locations with minimal temperature fluctuations. Rapid temperature changes during storage can cause condensation, resulting in lead oxidation or corrosion, which will deteriorate the solderability of the leads.
- When restoring devices after removal from their packing, use anti-static containers.
- Do not allow loads to be applied directly to devices while they are in storage.
- If devices have been stored for more than two years under normal storage conditions, it is recommended that you check the leads for ease of soldering prior to use.

Package Dimensions

Unit: mm



Weight: 0.08 g (typ.)

Package Name(s)
TOSHIBA: 11-4M1S

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